	Туре	L#	Hits	Search Text	DBs
1	IS&R	L1	2	(("6462426") or ("6075290")).PN.	USPAT
2	BRS	L2	910		US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L3	66		US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
4	IS&R	L4	1	("6964881").PN.	USPAT
5	BRS	L5	602	molding adj layer	USPAT
6	BRS	L6	0	5 with flowable with cured	USPAT
7	BRS	L7	1	5 with flow\$6 with cur\$6	USPAT
8	BRS	L8	1	5 with flow\$6 with cure\$6	USPAT
9	BRS	L9	18	5 with flow\$6	USPAT
10	BRS	L10	381	molding with flow\$6 with cure\$6	USPAT
11	BRS .	L11	63	10 and semiconductor	USPAT
12	BRS	L12	5	10 and (chip with backside)	USPAT